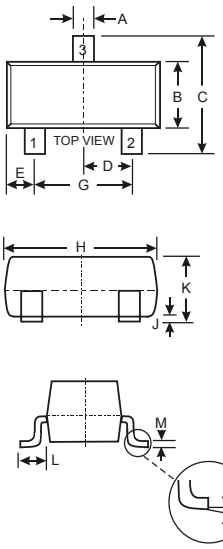
HAICHUANG SEMI

BAW156

DUAL SURFACE MOUNT LOW LEAKAGE DIODES

Features

- Surface Mount Package Ideally Suited for Automated Insertion
- Very Low Leakage Current

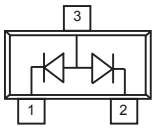


SOT-23		
Dim	**Min**	**Max**
A	0.37	0.51
B	1.20	1.40
C	2.30	2.50
D	0.89	1.03
E	0.45	0.60
G	1.78	2.05
H	2.80	3.00
J	0.013	0.10
K	0.903	1.10
L	0.45	0.61
M	0.085	0.180
α	0°	8°
All Dimensions in mm		

Maximum Ratings @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Unit	Value
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	85	V
RMS Reverse Voltage	$V_{R(RMS)}$	60	V
Forward Continuous Current (Note 1) Single diode Double diode	I_{FM}	 160 140	mA
Repetitive Peak Forward Current (Note 1)	I_{FRM}	500	mA
Non-Repetitive Peak Forward Surge Current @ t = 1.0μs @ t = 1.0ms @ t = 1.0s	I_{FSM}	 4.0 1.0 0.5	A
Power Dissipation (Note 1)	P_D	250	mW
Thermal Resistance Junction to Ambient Air (Note 1)	$R_{\theta JA}$	500	°C/W
Operating and Storage Temperature Range	T_J , T_{STG}	-65 to +150	°C

Top View
Internal Schematic



Electrical Characteristics @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	ConditiTeston
Reverse Breakdown Voltage (Note 2)	$V_{(BR)R}$	85	—	—	V	I_R = 100μA
Forward Voltage	V_F	—	—	0.90 1.0 1.1 1.25	V	I_F = 1.0mA I_F = 10mA I_F = 50mA I_F = 150mA
Leakage Current (Note 2)	I_R	—	—	5.0 80	nA nA	V_R = 75V V_R = 75V, T_J = 150°C
Total Capacitance	C_T	—	3	—	pF	V_R = 0, f = 1.0MHz
Reverse Recovery Time	t_{rr}	—	—	3.0	μs	I_F = I_R = 10mA, I_{rr} = 0.1 x I_R, R_L = 100Ω

Notes: 1. Part mounted on FR-4 board with recommended pad layout.
2. Short duration pulse test used to minimize self-heating effect.

TYPICAL TRANSIENT CHARACTERISTICS

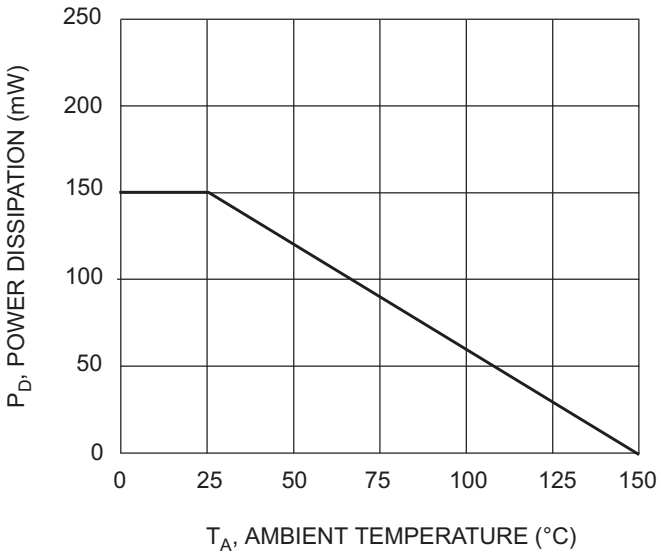


Fig. 1 Power Derating Curve

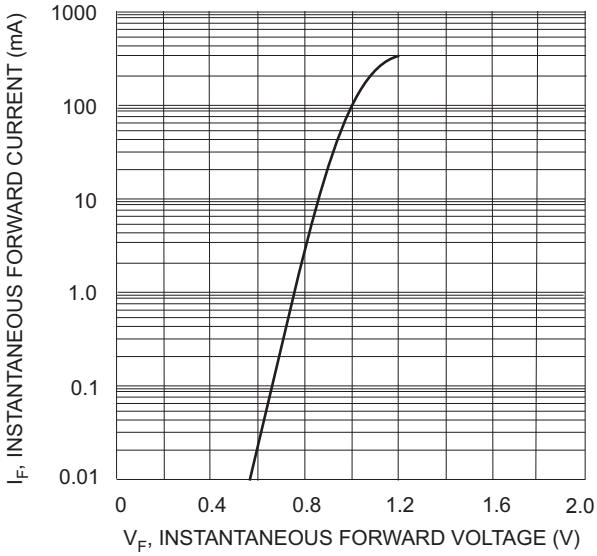


Fig. 2 Typical Forward Characteristics

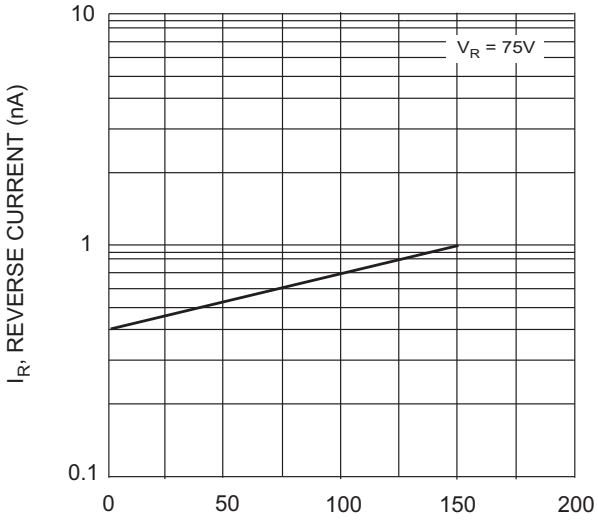


Fig. 3 Typical Reverse Characteristics

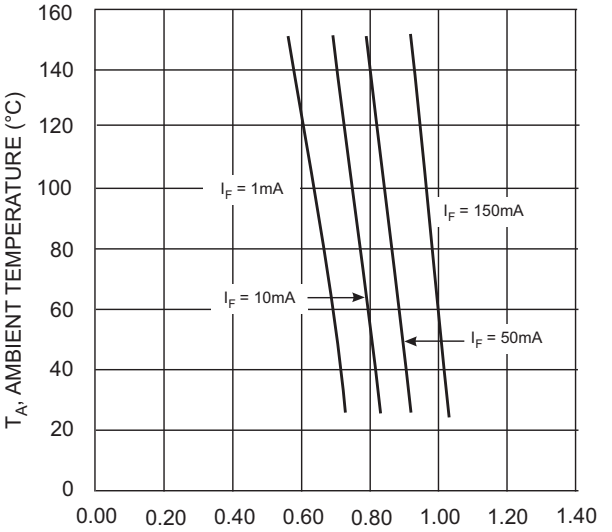


Fig. 4 Typical Forward Voltage vs Ambient Temperature

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